

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.

10/758,487

Confirmation No.:

Applicant(s):

HIROFUMI KURODA

Filed:

January 15, 2004

TC/A.U.

TBA

Examiner:

TBA

Title:

EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

**USING THEREOF** 

Docket No.:

033036.070

Customer No.:

25461

## MAIL STOP NONFEE AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## PRELIMINARY AMENDMENT

Prior to the first examination of the above-identified application, please amend the application as follows:

Amendments to the Specification are reflected beginning on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 12 of this paper.

## **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April 20, 2004.

Lucy Kinsey